

WE CLAIM:

1. A thermal head comprising:
 - a thermal radiating substrate;
 - a temperature keeping layer formed on the thermal radiating substrate;
 - a conductive layer formed on the thermal radiating substrate and an upper surface of the temperature keeping layer comprised of a fused material of nitride and metal or a fused material of oxide and metal;
 - a first interlayer insulation layer formed by oxidization of the conductive layer except a portion of the conductive layer corresponding to a common electrode and a portion of the common electrode corresponding to an external connecting common electrode terminal;
 - a second interlayer insulation layer comprised of insulating ceramics formed on the upper surface of the first interlayer insulation layer;
 - a heat generating resistor member formed above the second interlayer insulation layer and the conductive layer;
 - a common electrode and individual electrodes formed at a part of the upper surface of the heat generating resistor member; and
 - a protecting layer covering the heat generating resistor member, common electrode, individual electrodes and second interlayer insulation layer.
2. A thermal head according to Claim 1, wherein the second interlayer insulation layer is formed by insulating ceramics comprised of at least one of silicon nitride, silicon oxide, aluminum nitride or aluminum oxide.
3. A thermal head according to Claim 1, wherein at least more than three common electrode terminals of the common electrode for the external connection are formed in the thermal radiating substrate.
4. A thermal head according to Claim 1, wherein cutting planes of the temperature keeping layer, conductive layer, first interlayer insulation layer, second interlayer insulation layer and protecting layer at the cutting

plane of the thermal head cut in a direction perpendicular to arranging directions of a plurality of the heat generating resistor members are formed substantially in perpendicular to a plane of the thermal radiating substrate and the cutting plane at the thermal radiating substrate is substantially in flush with the cutting plane at the film layer portion.

5 5. A thermal head according to Claim 1, wherein cutting planes of the temperature keeping layer, conductive layer, first interlayer insulation layer, second interlayer insulation layer and protecting layer at the cutting plane of the thermal head cut in a direction perpendicular to arranging
10 directions of a plurality of the heat generating resistor members are formed substantially in perpendicular to a plane of the thermal radiating substrate and the cutting plane at the thermal radiating substrate forms a slant plane entered into the thermal radiating substrate.

~~6~~ A thermal head comprising:
15 a temperature keeping layer formed on the thermal radiating substrate;
 a conductive layer formed on the thermal radiating substrate, wherein one of silicon nitride, silicon oxide, aluminum nitride or aluminum oxide or these complex materials being applied as insulation material, and the
20 conductive layer being formed by conductive thermet comprised of fused material of this insulation material and metal of high melting point;
 a first interlayer insulation layer formed by oxidization of the surface of the conductive layer except a portion of the conductive layer
25 corresponding to a common electrode and a portion of the common electrode corresponding to an external connecting common electrode terminal;
 a second interlayer insulation layer comprised of insulating ceramics formed on the upper surface of the first interlayer insulation layer;
 a heat generating resistor member formed above the second interlayer insulation layer and the conductive layer;
30 a common electrode and individual electrodes formed at a part of the upper surface of the heat generating resistor member; and



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substrate;

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ceramics formed on the upper surface of the first interlayer insulation layer;

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of the upper surface of the heat generating resistor member; and

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